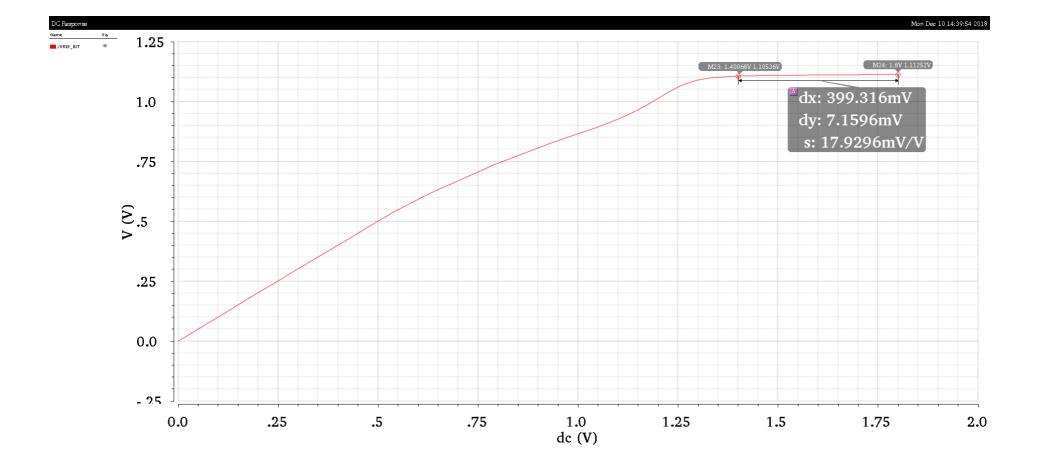


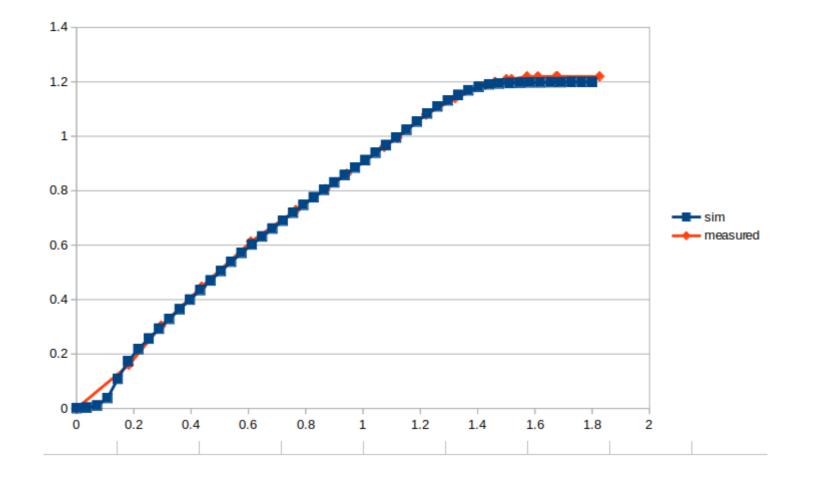
Bandgap Simulation - Vout vs Vin







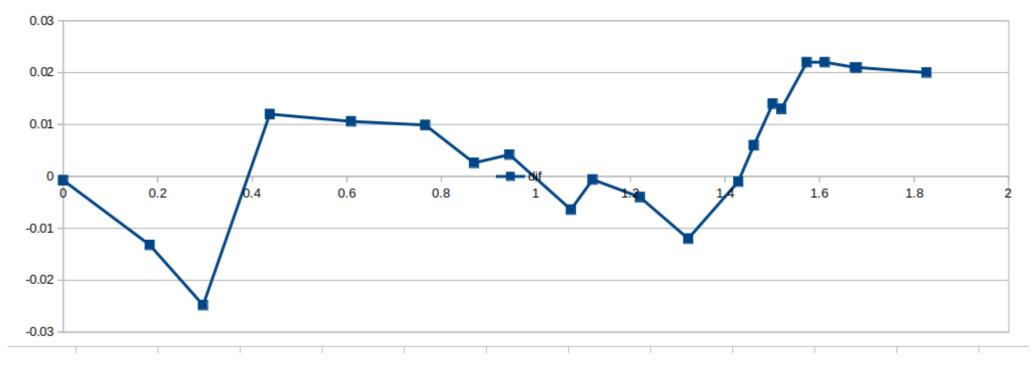
Bandgap Results - Vout vs Vin







Bandgap Results - Difference between simulation and Measuremtns Vs Vin

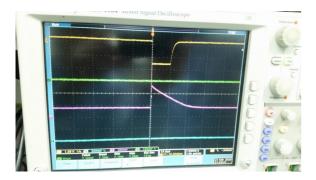


- Bandgap shows a maximum variation from simulation of $\approx 25 mV$
- Maximum variation from simulation of \approx 20mV over operating range (1.4 to 1.8V)



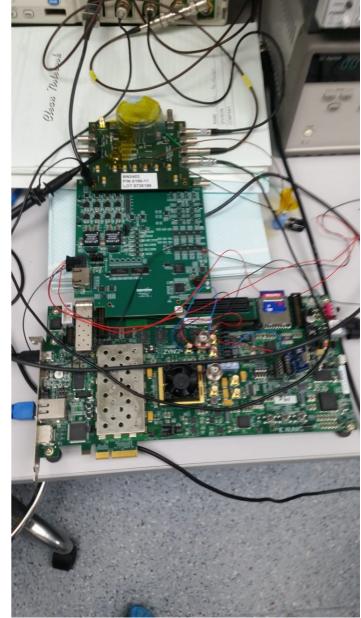


RD50 - MPW2 DAQ





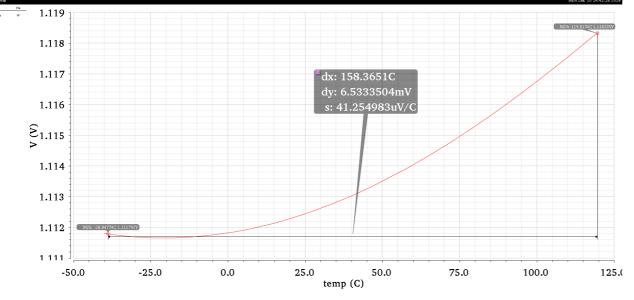
- RD50 MPW2 DAQ assembled
 - Firmware is tested but contains bugs
 - Analogue output measured
 - Compartator output measured
 - Bandgap voltage scan performed
- Helmut has noticed some issues with his firmware and is correcting the bugs
- Attempting to fix broken Caribou board and assemble second DAQ for use with MPW1 in parallel
- Attempt to improve firmware by adding delays had no effect for RD50-MPW1





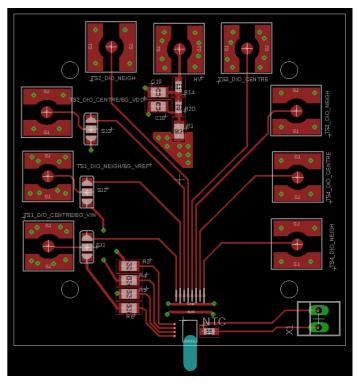


Bandgap Results - Temperature Scans



Further Testing

- Testing the bandgap over temperature with be the next step ٠
- We could do this with the existing setup and the climate ٠ chamber however this would mean monopolising the DAQ and putting \approx £4500 worth of equipment in an oven at 160 °C
- For this reason the TCT board has also been designed to • function as a testing platform for the bandgap, this will require only the relative cheap and simple TCT board be tested at extreme temperateues





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